

Metal Adhesion Promoters

PRODUCT DESCRIPTION

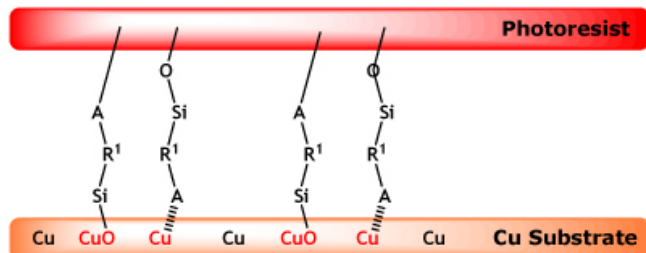
Shin-Etsu SIPR™-PR Series are specialty adhesion promoters designed to enhance the bonding of photoresist to copper or gold surfaces.

SIPR-PR1P is designed to enhance adhesion to copper, and utilizes two functional groups to provide chemical bonding to copper oxide and coordination to elemental copper.

SIPR-PR20P is designed to enhance adhesion to gold.

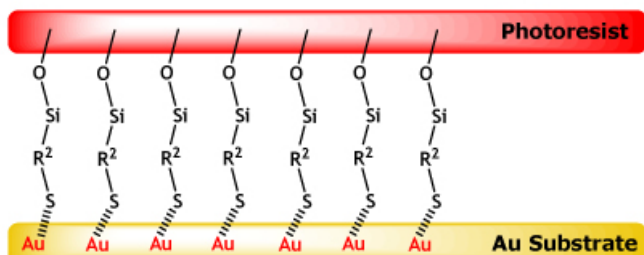
PROPERTIES

- SIPR-PR1P achieves a film thickness of ~ 3nm at 3000rpm
- SIPR-PR20P achieves a film thickness of ~ 5nm at 3000rpm
- Adhesion promoters can be readily removed with a fluorinated plasma
- SIPR-PR1P can also be readily removed with O₂ plasma

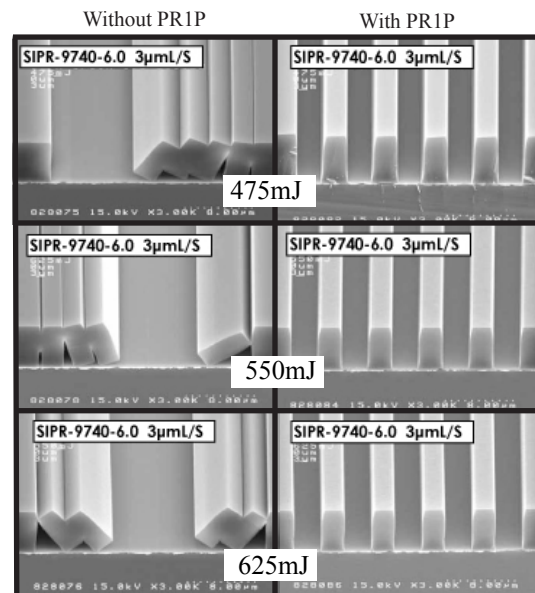


SIPR-PR1P

— Chemical Bonding - - - - - Coordination



SIPR-PR20P



SIPR-9740 on Copper
With and Without PR1P